

SRAM Reflow Soldering Conditions

Reflow soldering conditions	Note on reflow soldering	Applicable package	Applicable part name
Peak temperature: 260°C RDK-J-000068 	RDK-J-000076 	FBGA	R1LV1616HBG-4SI, R1LV1616HBG-5SI, RMLV0416EGBG-4S2, RMLV0816BGBG-4S2, RMLV1616AGBG-4U2, RMLV1616AGBG-5S2, RMLV1616AGBG-5U2, RMLV3216AGBG-5S2, RMWV3216AGBG-5S2, RMWV6416AGBG-5S2
	RDK-J-000074 	TSOP	R1LP5256ESA-5SI, R1LV5256ESA-5SI, R1LP0108ESA-5SI, R1LP0108ESF-5SI, R1LV0108ESA-5SI, R1LV0108ESF-5SI, R1LV0208BSA-5SI, R1LV0216BSB-5SI, R1LP0408DSB-5SI, R1LV1616HSA-4SI, R1LV1616HSA-5SI,
			R1RP0416DSB-0PI, R1RP0416DSB-0PR, R1RP0416DSB-2LR, R1RP0416DSB-2PI, R1RP0416DSB-2PR, R1RP0416DSB-2SR, R1RW0416DSB-0PI, R1RW0416DSB-0PR, R1RW0416DSB-2LR, R1RW0416DSB-2PI, R1RW0416DSB-2PR, R1RW0416DSB-2SR,
			RMLV0408EGSA-4S2, RMLV0408EGSB-4S2, RMLV0414EGSB-4S2, RMLV0416EGSB-4S2, RMLV0808BGSA-4S2, RMLV0816BGSA-4S2, RMLV0816BGSB-4S2, RMLV0816BGSD-4S2, RMLV1616AGSA-4U2, RMLV1616AGSA-5S2, RMLV1616AGSA-5U2, RMLV1616AGSD-5S2, RMLV3216AGSA-5S2, RMLV3216AGSD-5S2, RMWV6416AGSA-5S2, RMWV6416AGSD-5S2
Peak temperature: 245°C RDK-J-000070 	RDK-J-000074 	SOP(28-pin)	R1LP5256ESP-5SI, R1LV5256ESP-5SI
		SOP(32-pin)	R1LP0108ESN-5SI, R1LV0108ESN-5SI, R1LP0408DSP-5SI, RMLV0408EGSP-4S2
		SOJ	R1RP0408DGE-2LR, R1RP0408DGE-2PI, R1RP0408DGE-2PR, R1RW0408DGE-2LR, R1RW0408DGE-2PI, R1RW0408DGE-2PR, R1RP0416DGE-2LR, R1RP0416DGE-2PI, R1RP0416DGE-2PR, R1RP0416DGE-2SR, R1RW0416DGE-2LR, R1RW0416DGE-2PI, R1RW0416DGE-2PR

SRAM Baking (Moisture Desorption) Conditions

Baking conditions	Applicable package	Applicable part name
125°C, 8 ~ 24 hours RDK-J-000484 	FBGA	R1LV1616HBG-4SI, R1LV1616HBG-5SI, RMLV0416EGBG-4S2, RMLV0816BGBG-4S2, RMLV1616AGBG-4U2, RMLV1616AGBG-5S2, RMLV1616AGBG-5U2, RMLV3216AGBG-5S2, RMWV3216AGBG-5S2, RMWV6416AGBG-5S2
	TSOP	R1LP5256ESA-5SI, R1LV5256ESA-5SI, R1LP0108ESA-5SI, R1LP0108ESF-5SI, R1LV0108ESA-5SI, R1LV0108ESF-5SI, R1LV0208BSA-5SI, R1LV0216BSB-5SI, R1LP0408DSB-5SI, R1LV1616HSA-4SI, R1LV1616HSA-5SI, R1RP0416DSB-0PI, R1RP0416DSB-0PR, R1RP0416DSB-2LR, R1RP0416DSB-2PI, R1RP0416DSB-2PR, R1RP0416DSB-2SR, R1RW0416DSB-0PI, R1RW0416DSB-0PR, R1RW0416DSB-2LR, R1RW0416DSB-2PI, R1RW0416DSB-2PR, R1RW0416DSB-2SR, RMLV0408EGSA-4S2, RMLV0408EGSB-4S2, RMLV0414EGSB-4S2, RMLV0416EGSB-4S2, RMLV0808BGSB-4S2, RMLV0816BGSA-4S2, RMLV0816BGSB-4S2, RMLV0816BGSD-4S2, RMLV1616AGSA-4U2, RMLV1616AGSA-5S2, RMLV1616AGSA-5U2, RMLV1616AGSD-5S2, RMLV3216AGSA-5S2, RMLV3216AGSD-5S2, RMWV6416AGSA-5S2, RMWV6416AGSD-5S2
125°C, 20 ~ 72 hours RDK-J-000500 	SOP(28-pin)	R1LP5256ESP-5SI, R1LV5256ESP-5SI
	SOP(32-pin)	R1LP0108ESN-5SI, R1LV0108ESN-5SI, R1LP0408DSP-5SI, RMLV0408EGSP-4S2
	SOJ	R1RP0408DGE-2LR, R1RP0408DGE-2PI, R1RP0408DGE-2PR, R1RW0408DGE-2LR, R1RW0408DGE-2PI, R1RW0408DGE-2PR, R1RP0416DGE-2LR, R1RP0416DGE-2PI, R1RP0416DGE-2PR, R1RP0416DGE-2SR, R1RW0416DGE-2LR, R1RW0416DGE-2PI, R1RW0416DGE-2PR

SRAM Flow Soldering (Wave Soldering) Conditions

- Applicable to the lead type packages with the lead pitch greater than 0.65mm

Applicability	Package (pinout)	Lead pitch (mm)
OK	SOP(28), SOP(32), SOJ(36), SOJ(44)	1.27
OK	TSOP-II(32)	1.27
OK	TSOP-II(44)	0.8
Not Applicable	TSOP-I(28)	0.55
Not Applicable	sTSOP(32), TSOP-I(32), TSOP-I(48)	0.5
Not Applicable	uTSOP(52)	0.4
Not Applicable	FBGA(48) *BGA type is not applicable	0.75

Other Mounting-related Conditions

Title	Documentation
Partial Heating (Soldering Iron) Conditions	RDK-J-000072 
Storage Conditions Before Opening Moisture-Proof Packing	RDK-J-000061 
Storage Conditions After Opening Moisture-Proof Packing	RDK-J-000062 
Cleaning Conditions	RDK-J-000078 